

Equipment Loan Agreement

This ag	reement is	s made on DATE [] between:			
i.	Manager	ment & Science University (MSU), here	inafter referred to as "the University	y", and		
ii.	I, studen hereinafte	nt name [], stud	ent id [],	
Equipm	ent Detai	ls				
		Item Name	Item Reference	Quantity	Product Value (RM)	
	RASPBERRY PI 5 4GB BUNDLE KIT				550.00	
	NODEMCU ESP8266 ARDUINO MICROPYTHON WIFI DEVELOPMENT BOARD				17.00	
Terms a	and Condi	itions				
1.		rower acknowledges receipt of the above	ve-mentioned equipment for use in	n their final year proje	ct, Month/Year	
	[].				
2.	Loan Per	riod: From START DATE [].		
3.	The Borrower agrees to:					
	a) b) c) d)	b) The students are entitled to return all devices in working condition to the supervisor on the last day of the iREX semester.c) Return the equipment in the same condition as it was received, barring normal wear and tear.				
4.	Liability	:				
	 a) The Borrower is fully responsible for the equipment during the loan period. b) In case of damage, loss, or failure to return the equipment, the Borrower agrees to: Pay the full replacement cost of the equipment as per the product value listed Details table. Pay an additional fine of RM 150.00 Total liability in case of damage/loss will be calculated as follows: 					
	Total Liability Value: (Number of damaged/lost Raspberry Pi units × RM 550.00) + (Number of damaged/lost NodeMCU units × RM 17.00) + (RM 150.00 fine)					
5.	The Univ	ersity reserves the right to recall the eq	quipment at any time if these terms	are violated.		
By signir	ng below, th	e Borrower acknowledges that they have	ve read, understood, and agree to	the terms and conditions of	f this agreement.	
Borrower's Name: Borrowe			s Signature:	_ Date:		
Borrowe	er's IC Nun	nber:				
Universi	ty Represe	ntative: Ro	epresentative's Signature:	Date:		